



Material Content Data Sheet



Sales Product Name	IFX27001TF V26			Issued		25. September 2017		
MA#	MA000724048							
Package	PG-TO252-3-11			Weight*		401.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.924	0.73	0.73	7288	7288
leadframe	non noble metal	iron	7439-89-6	0.140	0.03		349	
	inorganic material	phosphorus	7723-14-0	0.042	0.01		105	
	non noble metal	copper	7440-50-8	139.706	34.82	34.86	348211	348665
wire	non noble metal	aluminium	7429-90-5	0.131	0.03	0.03	326	326
encapsulation	organic material	carbon black	1333-86-4	0.311	0.08		774	
	plastics	epoxy resin	-	14.284	3.56		35601	
	inorganic material	silicondioxide	60676-86-0	140.661	35.07	38.71	350593	386968
leadfinish	non noble metal	tin	7440-31-5	3.740	0.93	0.93	9322	9322
plating	non noble metal	nickel	7440-02-0	0.091	0.02		226	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	227
solder	noble metal	silver	7440-22-4	0.114	0.03		285	
	non noble metal	tin	7440-31-5	0.091	0.02		228	
	non noble metal	lead	7439-92-1	4.363	1.09	1.14	10875	11388
heatspreader	inorganic material	phosphorus	7723-14-0	0.028	0.01		71	
	non noble metal	iron	7439-89-6	0.095	0.02		236	
	non noble metal	copper	7440-50-8	94.488	23.55	23.58	235509	235816
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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